

Product Features

- High dynamic range downconverter with integrated LO, IF, & RF amps
- RF: 800 960 MHz
- IF: 200 250 MHz
- +37 dBm Output IP3
- +20 dBm Output P1dB
- 5 dB Noise Figure
- +5V Single supply operation
- Pb-free 6mm 28-pin QFN package
- · Low-side LO configuration
- Common footprint with other PCS/UMTS versions

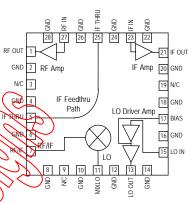
Product Description

The CV110-2A is a high linearity downconverter designed to meet the demanding issues for performance, functionality, and cost goals of current and next generation mobile infrastructure. It provides high dynamic range performance in a low profile surfacemount leadless package that measures 6 x 6 mm square.

Functionality includes RF amplification, frequency conversion and IF amplification, while an integrated LO driver amplifier powers the passive mixer. The MCM i implemented with reliable and mature GaAs MESFET and InGaP HBT technology.

Typical applications include frequency downconversion used in CDMA/GSM/TDMA, CDMA2000, W-CDMA and EDGE 2.5G and 3G mobile base transceiver stations for cellular frequency bands.

Functional Diagram



Specifications (1)

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Parameters	Units	Min		Max	Comments
RF Frequency Range	MHz		800 - 960	/	
LO Frequency Range	MHz		550 760		
IF Center Frequency Range	MHz		200 - 250		See note 2
% Bandwidth around IF center frequency	%		±7.5		See note 3
IF Test Frequency	MHz	V / 1/1/	240		
SSB Conversion Gain	dB		22		Temp = 25 °C
Gain Drift over Temp (-40 to 85 °C)	dB		±1.5		Referenced to +25 °C
Output IP3	dBm		+37		See note 4
Output IP2	dBm	/// \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	+45		See note 4
Output 1dB Compression Point	dBm		+20		
Noise Figure	dB ?		5		See note 5
LO Input Drive Level	dBm	2.5	0	+2.5	
LO-RF Isolation	2 gB/	\sim	60		See note 6
LO-IF Isolation	(dB)		40		$P_{LO} = 0 \text{ dBm}$
Return Loss: RF Port	(B)	ľ	15		
Return Loss: LO Port	dB		10		
Return Loss: IF Port	(B)		15		
Operating Supply Voltage	V	+4.9	+5	+5.1	
Supply Current	→ mA	290	360	480	
FIT Rating	failures/1E9 hrs			72.1	@ 70° C ambient, 90% confidence
Thermal Resistance	°C / W			27	
Junction Temperature	°C			160	See note 7

Absolute Maximum Rating

Parameter	Rating
Operating Case Temperature	-40 to +85 °C
Storage Temperature	-55 to +125 °C
DC Voltage	+6 V
Junction Temperature	+220 °C
RF Input (continuous)	+2 dBm

Operation of this device above any of these parameters may cause permanent damage.

End of Life Notice

Last time buy date: Oct. 9, 2010 Recommended replacement part: CV110-3AF

Ordering Information

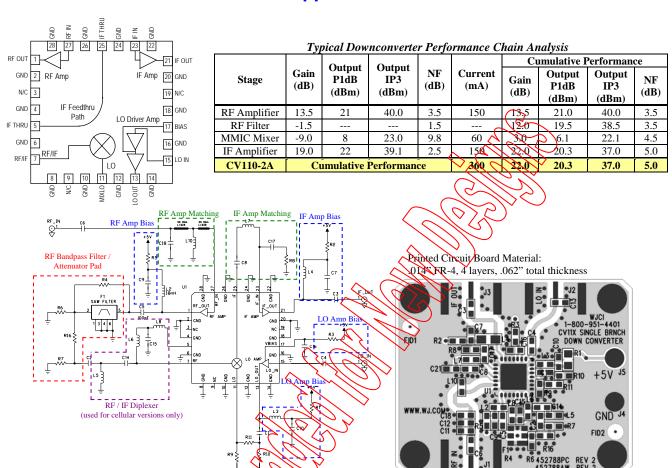
Part No.	Description
CV110-2AF	Cellular-band High Linearity Downconverter (lead-free/RoHS-compliant 6x6mm OFN package)
CV110-2APCB240	Fully Assembled Eval. Board, IF = 240MHz

Specifications and information are subject to change without notice

Specifications when using the application specific circuit (shown on page 3) with a low side LO = 0 dBm in a downconverting application over the operating case temperature range. If matching components affect the center frequency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications engineering@wj.com. The IF bandwidth of the converger is befored as 15% around any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around the total $\pm 7.5\%$ bandwidth is, within center frequency of 240 MHz, the specifications are valid from 240 \pm 18 MHz. Assumes the supply voltage \pm V. OIP3 is measured with $\Delta f = 1$ MHz with IF out \pm 5 dBm / tone. Assumes LO injection rough is influence at the thermal noise floor, -174 dBm/Hz, at the RF, IF, and flange frequencies. L-R Isolation is referenced to as LO piction of 0 dBm. The L-R performance shown also includes the isolation due to an external SAW filter between the RF amplifier and mixer. The maximum junction temperature ensures a minimum MTTF rating of 1 million hours of usage.



Device Architecture / Application Circuit Information



CV110-2A: The application circuit can be broken up into four main functions as denoted in the colored dotted areas above. RF/IF diplexing (purple), amplifier matching (green), futering (red), and de biasing (blue). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ single-branch converters. Additional placeholders for other optional functions such as filtering are also included.

RF / IF Amplifier Matching: The RF amplifier requires a shunt matching element for optimal gain and input return loss performance. The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be found in the IF Amplifier Matching Table or by e-mailing to sicapplication.engineering@tqs.com.

RF Bandpass Filtering: Bandpass filtering is recommended to reject the image frequencies and achieve the best noise figure

performance with the downconverter. The bandpass filter, implemented with a SAW filter on the application circuit, allows for the suppression of noise from the image frequency. It is permissible to not use a filter and use a 2 dB pad with R6, R7, and R16 instead with slightly degraded noise figure performance. Standard WJ evaluation boards will have the 2 dB pad in place.

External Diplexer: In a downconversion application, the incoming RF signal impinges on the switching elements of the mixer; the interaction with these switches produces a signal at the IF frequency. The two signals (RF and IF) are directed to the appropriate ports by the external diplexer. Pin 5 contains the IF signal and allows the signal to be transferred to pin 25 for the convenience of PCB layouts.

DC biasing: DC bias must be provided for the RF, LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

IF Amplifier Matching

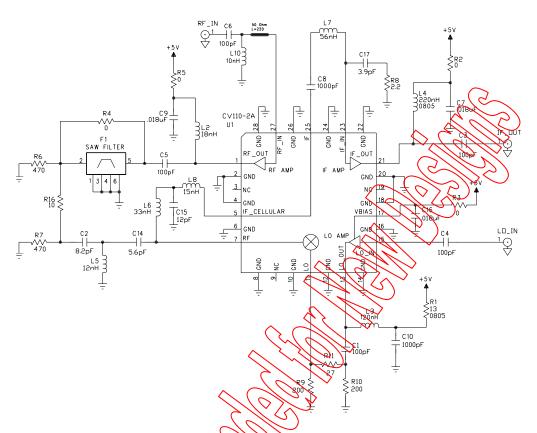
Frequency (MHz)	40	50	75	100	125	130	155	169	180	210	240
L7 (nH)	470	430	150	150	120	120	100	82	82	82	56
C17 (pF)	24	15	22	10	8.2	6.8	5.6	5.0	4.7	3.3	3.9
R8 (ohms)	4.7	4.7	3.3	2.2	2.2	2.2	2.2	2.2	2.2	2.2	2.2
L4 (nH)	470	240	330	330	330	330	330	330	330	220	220

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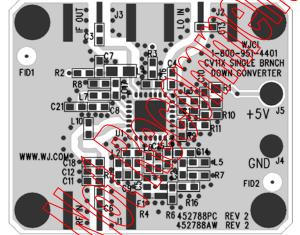




Downconverting Application Circuit: CV110-2APCB240 RF = 800 - 960 MHz, IF = 240 MHz



PCB Layout



Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

Bill of Materials

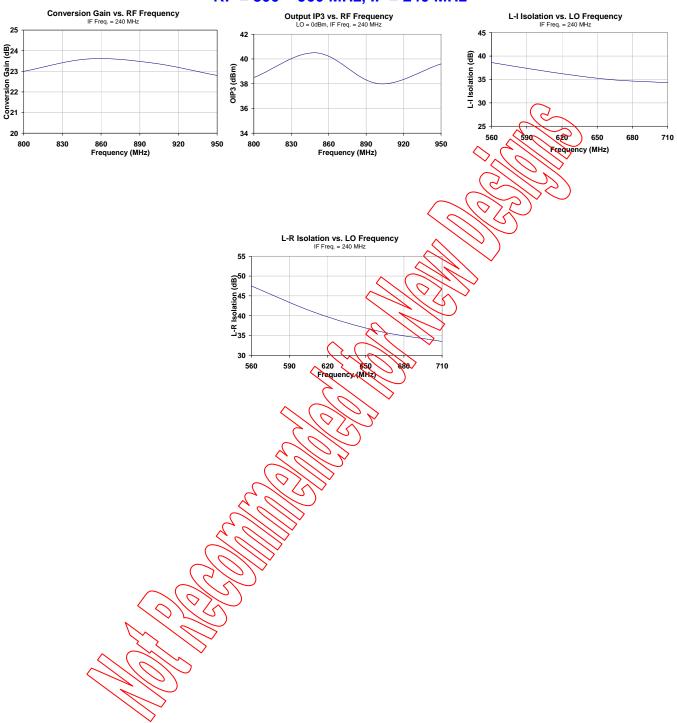
Ref. Desig.	Component
R1	13 Ω chip resistor, size 0805
R2, R3, R4, R5	0 Ω chip resistor
R6, R7	470 Ω chip resistor
R8	2.2 Ω chip resistor
R9, R10	200 Ω chip resistor
R11	27 Ω chip resistor
R16	10 Ω chip resistor
C1, C3, C4, C5, C6	100 pF chip capacitor
C2	8.2 pF chip capacitor
C7, C9, C16	0.018 μF chip capacitor
C8, C10	1000 pF chip capacitor
C11, C12, C13,	Shown in silkscreen, but not
C18, C21, F1	used in actual circuit.
C14	5.6 pF chip capacitor
C15	12 pF chip capacitor
C17	3.9 pF chip capacitor
C18	1.5 pF chip capacitor
L2	18 nH chip inductor
L3	120 nH chip inductor
L4	220 nH chip inductor, size 0805
L5	12 nH chip inductor
L6	33 nH chip inductor
L7	56 nH chip inductor
L8	15 nH chip inductor
L10	10 nH chip inductor
U1	CV110-2A WJ Converter

All components are of size 0603 unless otherwise specified.





CV110-2APCB240 Application Circuit Performance Plots RF = 800 - 960 MHz, IF = 240 MHz

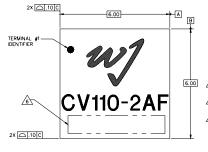




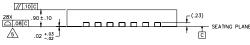
Mechanical Information

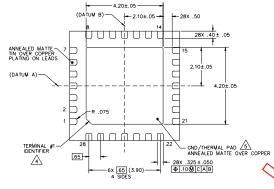
This package is lead-free/RoHS-compliant. The plating material on the pins is annealed matte tin over copper. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes.

Outline Drawing

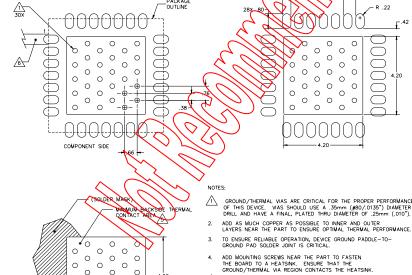


- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.
- 6.00 A THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JESD 95-1 SPP-012.
 - COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
 - ALPHA-NUMERIC LOT CODE.





Mounting Configuration / Land Pattern



0 0

0 0 0

0 0 0

0 0 0

0 0 0

BACK SIDE

0 0

4.20

0

Product Marking

The component will be lasermarked with a "CV110-2AF" product label with alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes' section.

ESD/MSI Information

Caution! ESD sensitive device.

ESD Rating Class 1B

Passes $\geq 500V$ to <1000VValue: Human Body Model (HBM) Test:

Standard: JEDEC Standard JESD22-A114

ESD Rating: Class III

Value: Passes $\geq 500V$ to <1000VCharged Device Model (CDM) Test: JEDEC Standard JESD22-C101 Standard:

MSL Rating: Level 2 at +260 °C convection reflow Standard: JEDEC Standard J-STD-020

Functional Pin Layout

Pin	FUNCTION	Pin	FUNCTION		
1	RF Amp Output	15	LO Amp Input		
2	GND	16	GND		
3	N/C	17	LO Amp Bias		
4	GND	18	GND		
5	IF Feedthru Port	19	N/C or GND		
6	GND	20	GND		
7	Mixer RF / IF Port	21	IF Amp Output/Bias		
8	GND	22	GND		
9	N/C or GND	23	IF Amp Input		
10	GND	24	GND		
11	Mixer LO Input	25	IF Feedthru Port		
12	GND	26	GND		
13	LO Amp Output	27	RF Amp Input		
14	GND	28	GND		

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USE 1 OZ. COPPER MINIMUM.

DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.

ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

AND CONSTRUCTION.